

ABSTRACT OF THE DISCLOSURE

A capacitor includes a semiconductor substrate, a bottom
conductive pattern, first to third insulating layers, first
5 to third metal plates and a connecting pattern. The bottom
conductive pattern is formed on the semiconductor substrate.
The first to third insulating layers are formed on the bottom
conductive pattern, the first and second metal plates,
respectively. The first metal plate is formed on the first
10 insulating layer within a first area. The first metal plate
is electrically connected to the bottom conductive pattern.
The second metal plate is formed on the second insulating layer
within the first area. The second metal plate has an opening
in the center thereof. The third metal plate is formed on the
15 third insulating layer. The connecting pattern is formed
through the second and third insulating layers and the opening
of the second metal plate. The connecting pattern electrically
connects the first and the third metal plate.